Organizers

VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM)

Dr.-Ing. Ronald Schnabel Stresemannallee 15

60596 Frankfurt/Main, Germany

Phone: +49-69-6308 227 +49-69-6308 9828 Fax: E-Mail: gmm@vde.com

In cooperation with:

UBC Microelectronics Dr. Uwe Behringer EMLC 2014 Conference Chair Auf den Beeten 5

72119 Ammerbuch, Germany Phone: +49-171-455-3196 +49-7073-50216

E-Mail: uwe.behringer.ubc@t-online.de

Venue: Hilton Hotel in Dresden





Dresden at the river Flbe

The EMLC 2014 International Program Committee

Conference Chair Uwe Behringer.

UBC Microelectronics. Ammerbuch, Germany

Co-Conference Chairs Naoya Hayashi, DNP, Saitama, Japan

Chris Gale, Applied Materials, Dresden,

Germany

Brid Connolly, Toppan Photomasks

GmbH, Dresden, Germany

Wilhelm Maurer, Infineon Technologies Program Chair

AG. Munich. Germany

Co-Program Chairs Rolf Seltmann, Globalfoundries,

Dresden, Germany

Jo Finders, ASML, Veldhoven,

Netherlands

Other Members

Michael Arnz, Carl Zeiss SMT AG, Oberkochen, Germany Carola Blaesing, Carl Zeiss SMS GmbH, Jena, Germany Parkson Chen, Taiwan Mask Corp., Hsinchu, Taiwan Greg Hughes, SEMATECH, Albany, NY, USA Rik Jonckheere, IMEC, Leuven, Belgium Kurt Kimmel, SEMATECH, Albany, NY, USA Barbara Lauche, Photronics MZD GmbH, Dresden, Germany

Hans Löschner, IMS Nanofabrication AG, Vienna, Austria Chris Progler, Photronics Inc., USA

Emmanuel Rausa, Plasma-Therm USA, St Petersburg, FL, USA Douglas J. Resnick, Molecular Imprints, Austin, TX, USA Klaus-Dieter Röth, KLA-Tencor MIE, Weilburg, Germany Carmelo Romeo, Numonyx, Agrate Brianza, Italy Hella Scheer, University of Wuppertal, Germany Thomas Scherübl, Carl Zeiss SMS GmbH, Jena, Germany

Ronald Schnabel, VDE/VDI-GMM, Frankfurt, Germany Steffen Schulze, Mentor Graphics Corp. Wilsonville, OR, USA

Mark Staples, Globalfoundries, Dresden, Germany Ines Stolberg, Vistec Electron Beam GmbH, Jena, Germany

Serge Tedesco, CEA-LETI, Grenoble, France

Michel Tissier, Toppan Photomasks S.A., Rousset, France Jacques Waelpoel, ASML, Veldhoven, Netherlands

Guido Wenz, Wenz Consulting, Weil im Schoenbuch, Germany

John Whittey, KLA-Tencor, San José, USA

Hermann Wolf, Photronics MZD GmbH, Dresden, Germany Stefan Wurm, SEMATECH, Albany, NY, USA

Larry Zurbrick, Agilent Technologies, Santa Clara, CA, USA

VDE/VDI-GESELLSCHAFT MIKROELEKTRONIK, MIKROSYSTEM-UND FEINWERKTECHNIK



June 24 - 25, 2014 Hilton Hotel Dresden, Germany



www.EMLC2014.com





The VDE/VDI-Society Microelectronics, Microsystems and Precision Engineering (GMM) and UBC Microelectronics in cooperation with BACUS, PMJ, and SPIE, are pleased to announce the



Hilton Hotel Dresden, Germany

June 24 - June 25, 2014

The focus of this 2-day conference is state-of-the-art of mask technology and lithography, such as mask manufacturing, mask business, lithography and mask applications, emerging mask & lithography technologies, and mask & lithography equipment.

This conference has annually brought together scientists, researchers, engineers and developers from around the world to present papers at the forefront of research, manufacturing and application. It provides a place where mask makers, mask users, and their tool suppliers become acquainted with new developments and results.

Technical Exhibition

On Tuesday and Wednesday (June 24th and 25th 2014) there will be a technical exhibition with booth space for about 30 exhibitors. Presentation tables and pin boards will be available. If you would like to take part in this Technical Exhibition, please return the enclosed registration form to the conference chairperson as soon as possible, since exhibition space is limited.

Conference Chair and Exhibition Organization

Dr. Uwe Behringer, UBC Microelectronics, Auf den Beeten 5, D-72119 Ammerbuch, Germany

D-72119 Ammerbuch, Germany Phone: +49-171-4553196

Fax: +49-7073-50216

E-Mail: uwe.behringer.ubc@t-online.de

Abstract Information

Abstract quality will be the basis for selection of conference presentations. The abstracts will be assessed for:

- Originality of work
- Specific results reported
- · Potential impact and interest to the attendees.

Therefore, we highly recommend that your abstract contains enough detail to clearly describe the content of your presentation. We recommend an abstract length of two pages including (figures, diagrams, formatted text) as Word and PDF.

Commercial papers, papers with no new research / development content, and papers where significant information is missing will not be accepted.

All accepted abstracts will be printed, bound and handed out to the participants of the conference.

In order to submit your abstract, please open the web site

www.EMLC2014.com

There you will find a link for paper submission at SPIE

■ Deadline for Abstracts: Friday, March 21st 2014

> By submitting an abstract you agree to

- · Present your work personally at the conference and
- Submit a manuscript in time

Authors will be notified of the acceptance of their submissions by **April 4th 2014**; further manuscript format and layout instructions will be provided at that time.

Manuscripts:

Please submit the original of the manuscript as early as possible, but do not miss the

■ Deadline for Manuscripts: camera ready June 24th 2014

Further information on the submission procedure can be found at www.emlc2014.com.

All manuscripts will be subjected to a critical peer review before they are accepted for publication.

Please note that late submissions may not be published.

Manuscripts will be published by SPIE, also on the SPIE Digital Library, so please follow the instructions provided at http://spie.org/x14101.xml

Conference Topics

Presentations are solicited for the following and related topics:

Mask Manufacturing

- Mask Data Preparation
- Pattern Generation: Writing, Etch, etc.
- Photomask Processes & Materials
- Metrology Tools & Technologies
- Defect Inspection & Repair
- Cleaning & Haze
- Pellicles & Mask Boxes
- Mask Process Yield & Cycle Time
- Photomasks for RET & OPC; PSM
- Masks for NGL: E-Beam, EUV, NIL, etc.

Mask Business

- Mask Business and Management
- Mask Cost and Mask Development Strategy
- Future Mask Demand

Lithography and Mask Application

- Double Patterning
- RET, OPC, PSM, MEEF
- Resist
- Mask Defect Printability
- Optical Materials
- Immersion Lithography
- Immersion Defectivity
- Alternate Immersion Fluids
- Lithography Process Control
- Lithography Simulation

Emerging Mask and Lithography Technologies

- EUV Materials, Tools & Processes
- EUV Mask Infastructure
- NII
- Direct Write / Maskless Technologies

Mask and Lithography Equipment

Mask Manufacturing

Semiconductors applied in Automotive

Semiconductors in MEMS Applications

Patterned Media